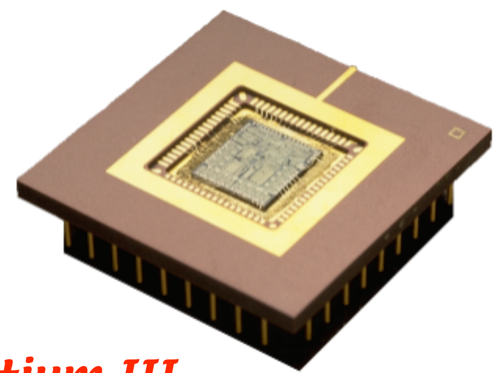
Thermal Design and Optimization of Heat Sinks

J. Richard Culham

Outline

- Background
- Modelling Approach
- Validation
- Optimization
- Future Work
- Summary

40 Watts! What's the big deal?



Pentium III

- 0.25 micron CMOS technology
- 9.5 million transistors
- 450 - 550 MHz

Light Bulb

- Power: 40 W
- Area: 120 cm^2
- Flux: 0.33 W/cm^2

Silicon

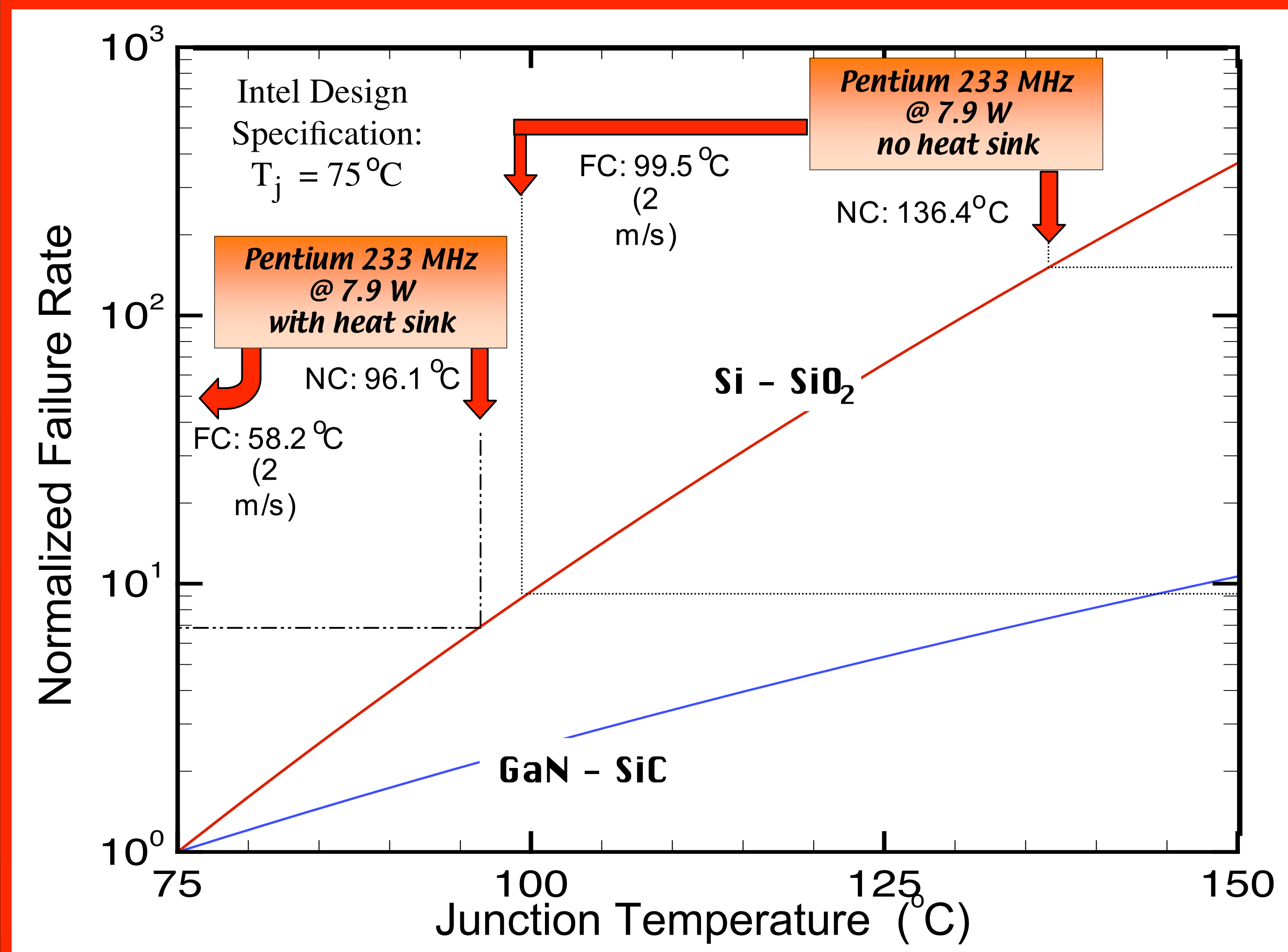
- Power: 40 W
- Area: 1.5 cm^2
- Flux: 26.7 W/cm^2

Package

- Rj-c: 0.94 C/W
- Rj-a: 6.8 C/W (no heat sink)
- Rj-a: 2.5 C/W (heat sink)

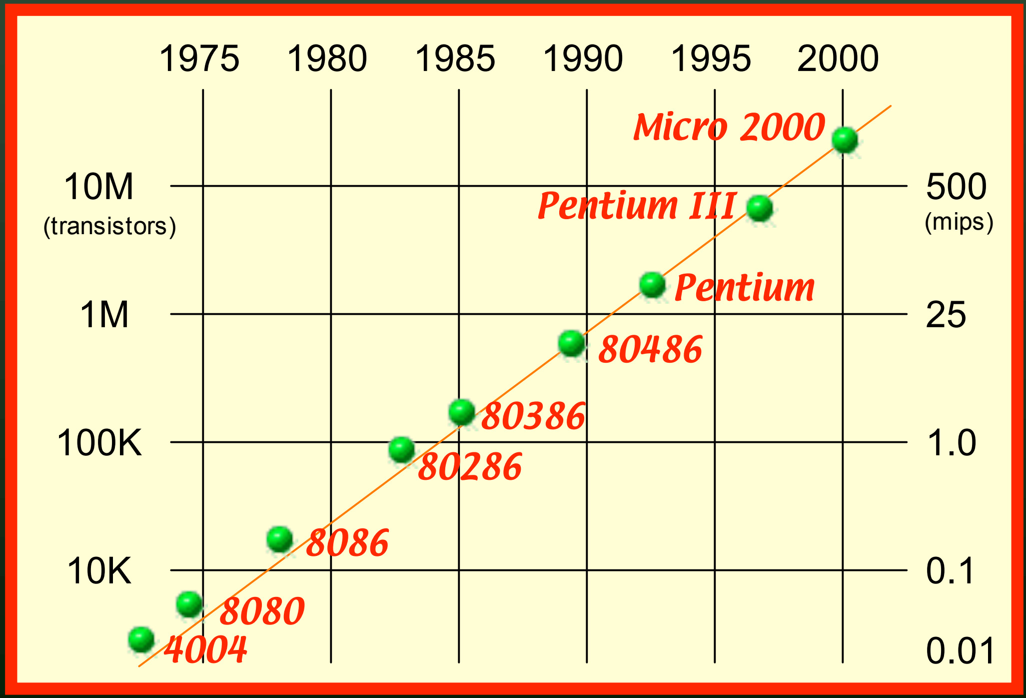
80 x

Component Failure Rate



Moore's Law (1965)

- each new chip contains roughly twice as much capacity as its predecessor
- a new generation of chips is released every 18 - 24 months



From: www.intel.com

- *in 26 years, the population of transistors per chip has increased by 3,200 times*

IC Trends: Past, Present & Future

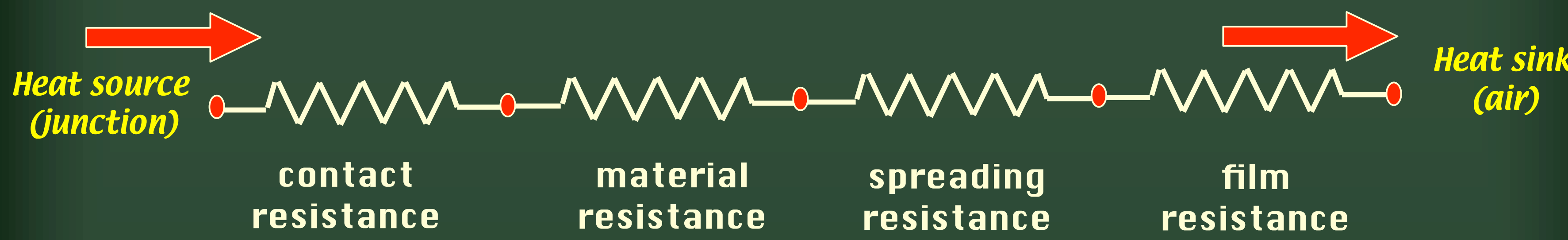
	1980	1999	2003	2006	2012
Comp. Per Chip	0.2 M	6.2 M	18 M	39 M	100 M
Frequency (MHz)	5	1250	1500	3500	10000
Chip Area (sq. cm)	0.4	4.45	5.60	7.90	15.80
Max. Power (W)	5	90	130	160	175
Junction Temp. (C)	125	125	125	125	125

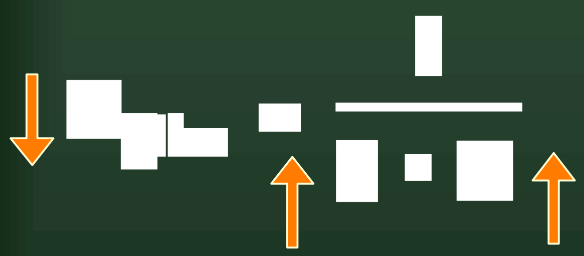
From: David L. Blackburn, NIST

Why Use Natural Convection?

- simplicity:
  - low maintenance
  - lower power consumption
  - less space (notebook computers)
- less noise
- fail safe heat transfer condition

Thermal Resistance





- increased heat transfer coefficient
  - ↪ immersion cooling (boiling)
  - ↪ impingement cooling
  - ↪ forced air
  - ↪ natural convection
- increased surface area
  - ↪ spreaders
  - ↪ heat sinks

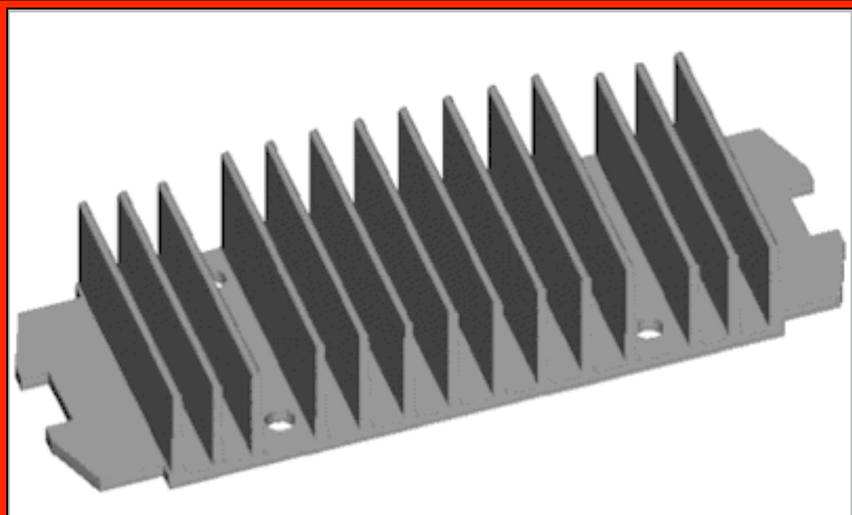
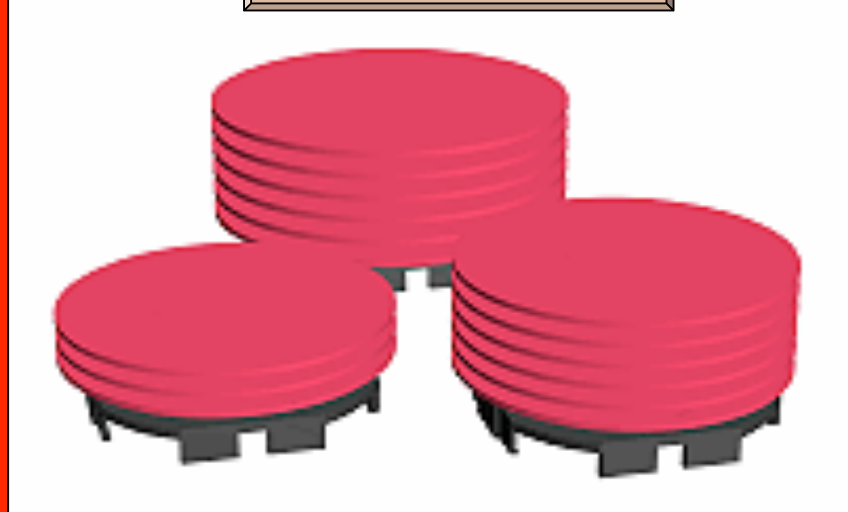


Plate Fin H.S.

Pin Fin H.S.

Radial Fin H.S.



Specialty H.S.

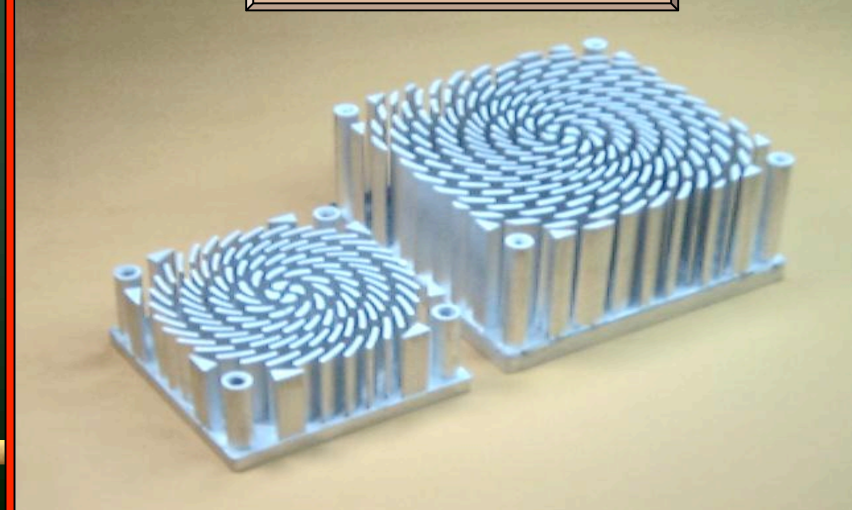
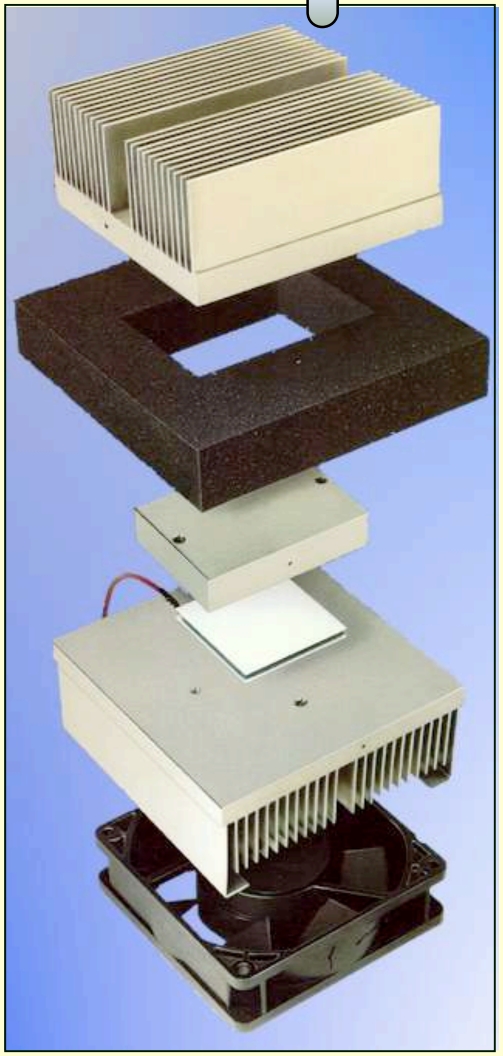
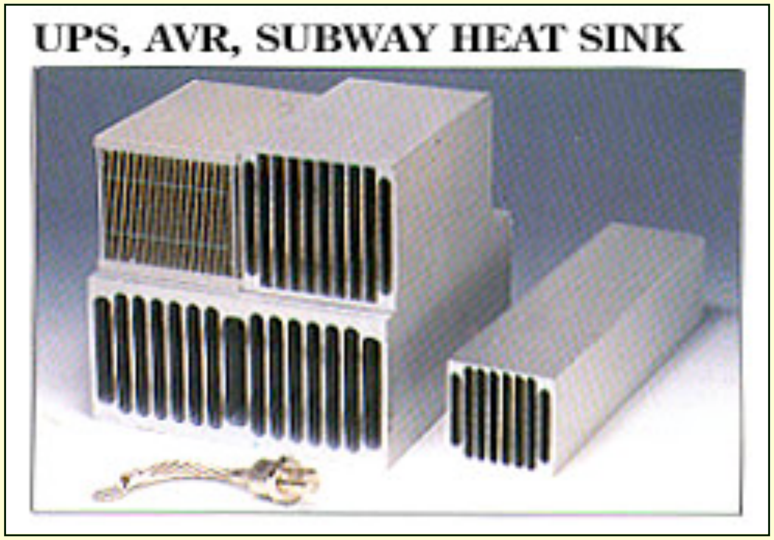
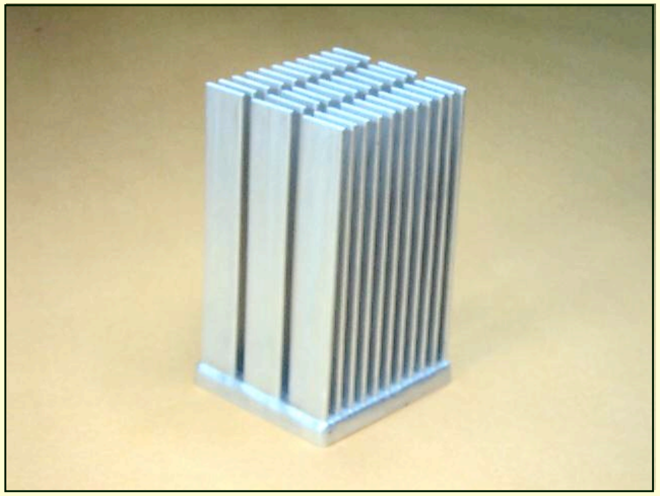


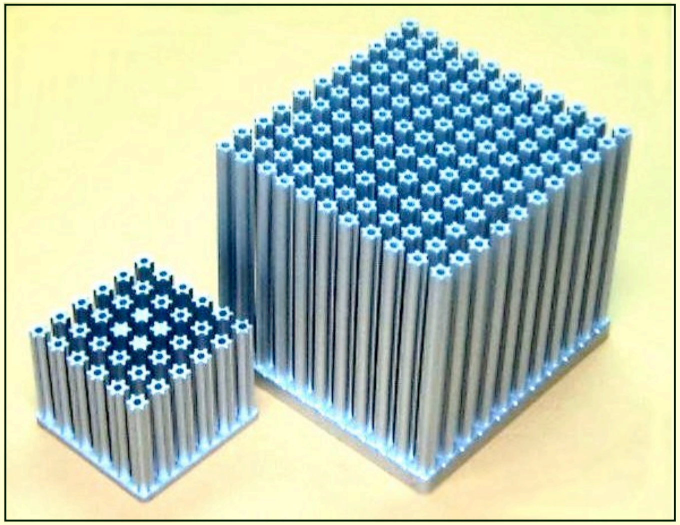
Plate Fin Heat Sinks

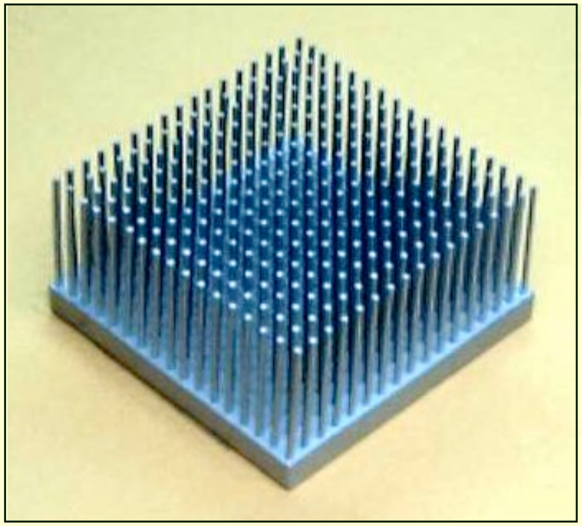


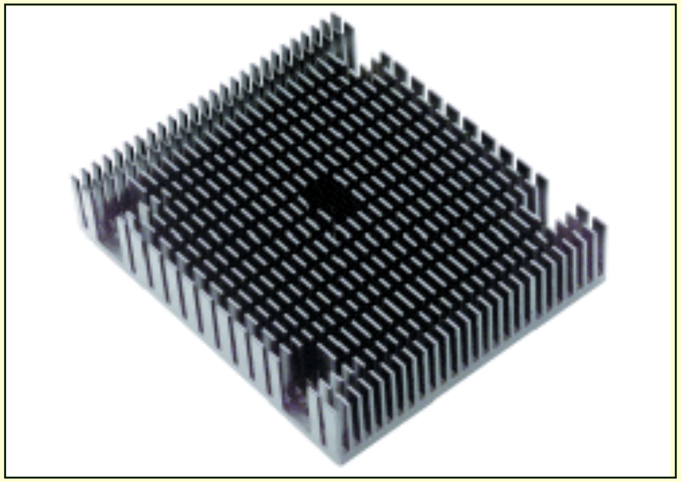




Pin Fin Heat Sinks

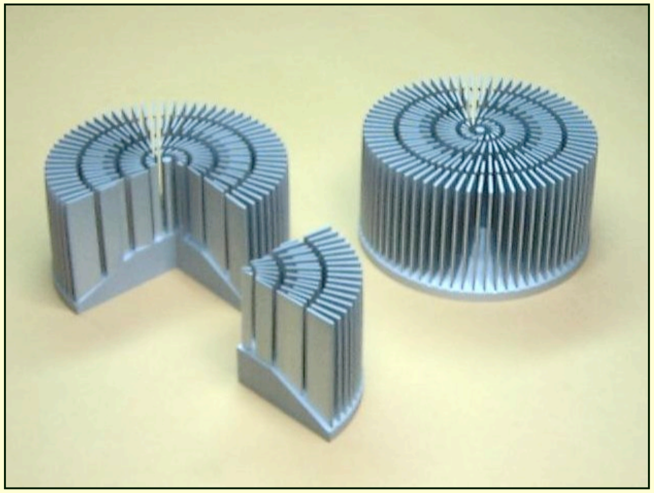


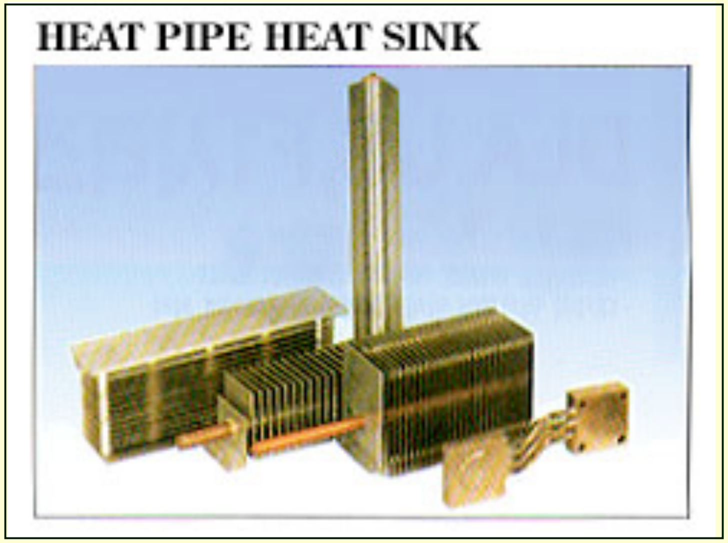


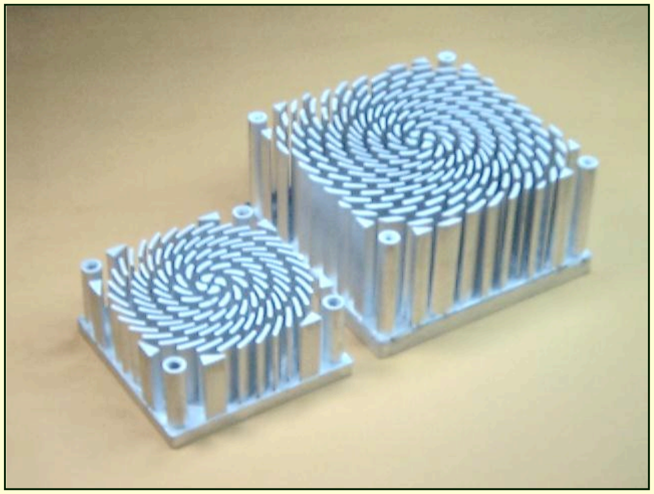


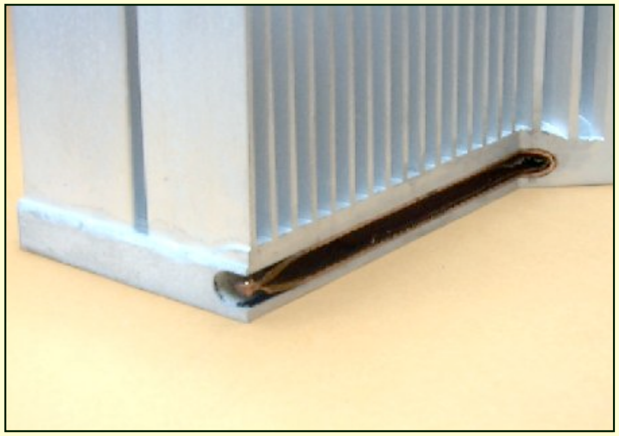
Radial Fin Heat Sinks

Specialty Heat Sinks





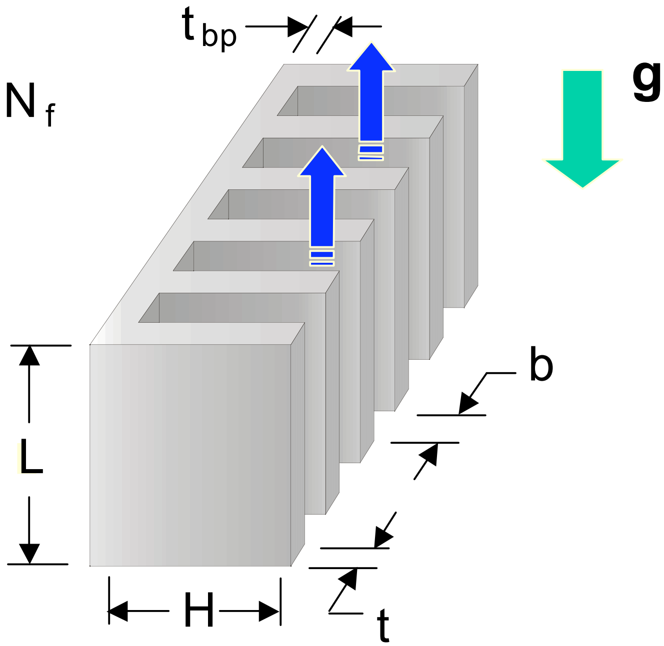




Heat Sink Model

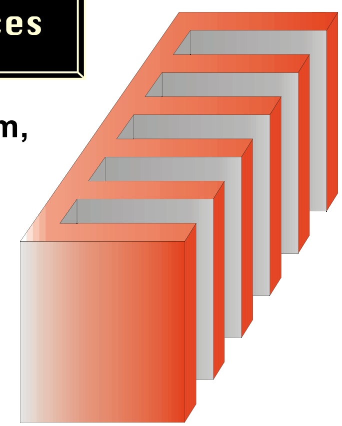
- Plate fin heat sink
- Natural convection
- Isothermal
- Steady state
- Working fluid is air i.e. $Pr = 0.71$

Modelling Procedure



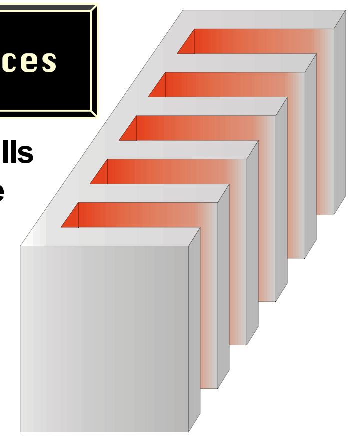
Exterior surfaces

- fins : top, bottom, ends & tip
- base plate: top, bottom, ends and back



Interior surfaces

- fins : side walls
- channel base



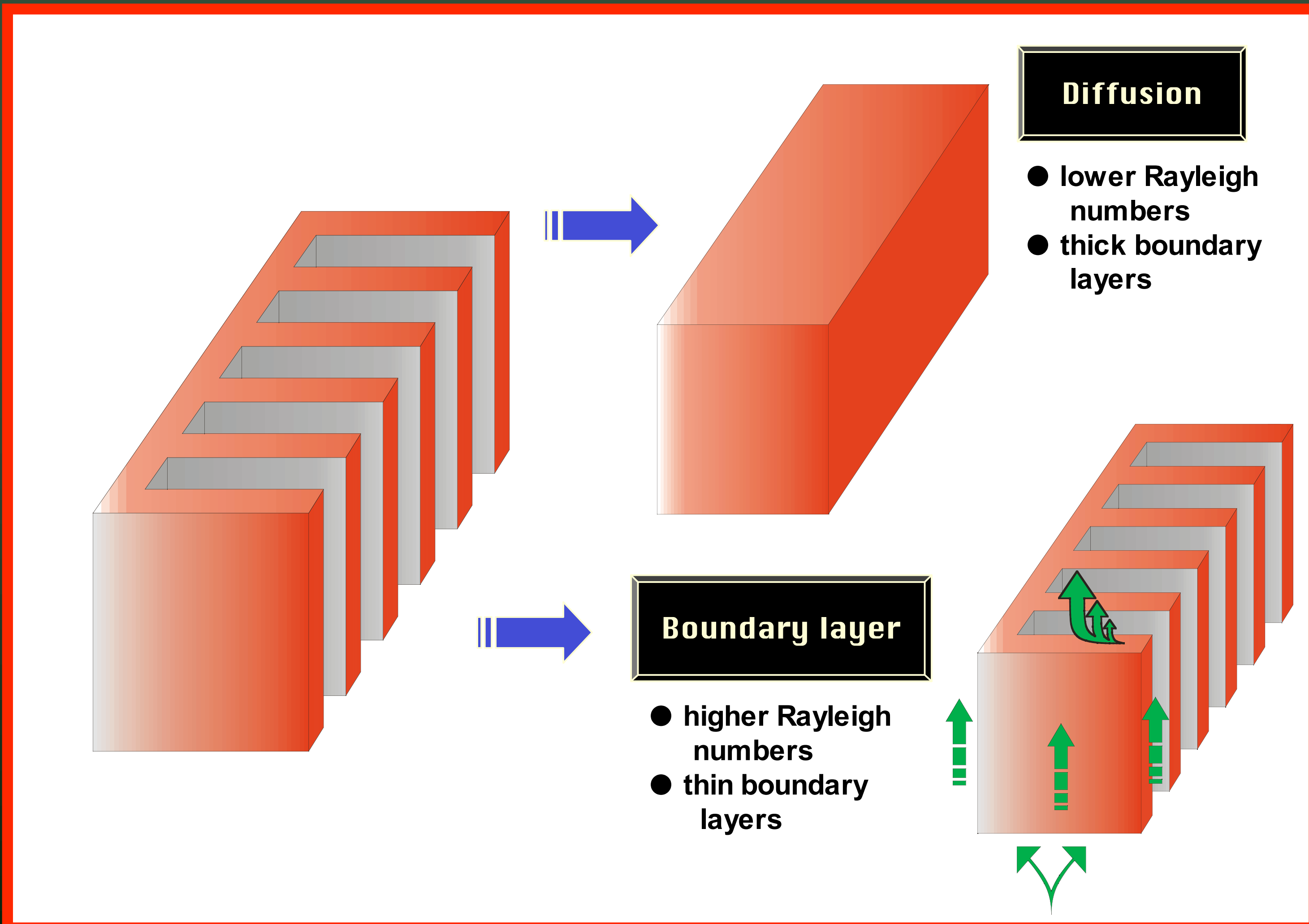
Given: dimensions & temperature

Find: Nu_b *vs.* Ra_b

$$Nu_b = \frac{hb}{k_f}$$

$$Ra_b = \frac{g \beta \Delta T b^3}{\alpha \nu} \bullet \frac{b}{L}$$

Exterior Surfaces



Diffusion Model

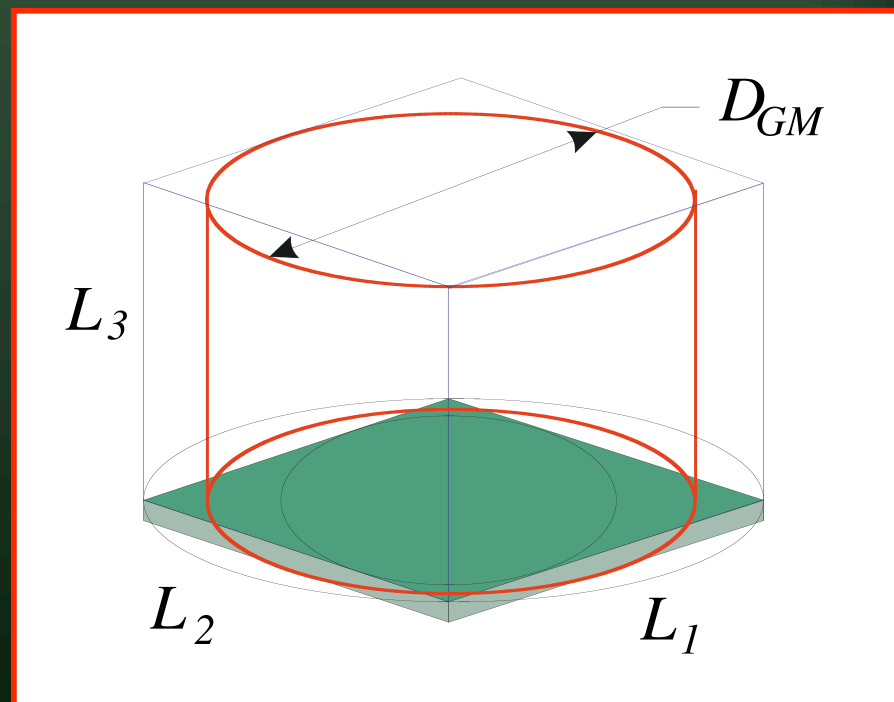
[illegible]

[illegible]

[illegible]

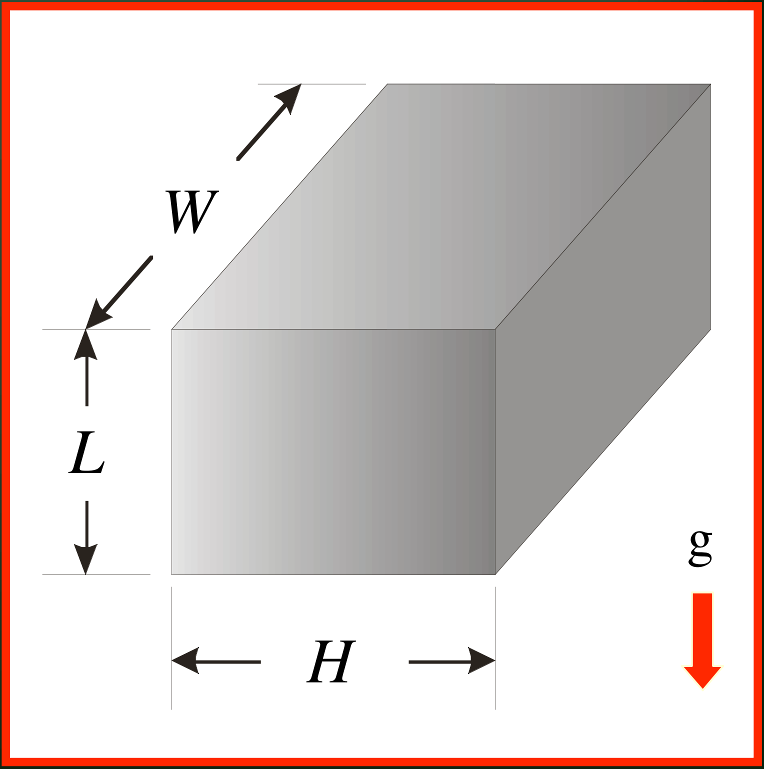
[illegible]

[illegible]



Exterior Boundary Layer Model

[illegible] *(in terms of the surface area)*



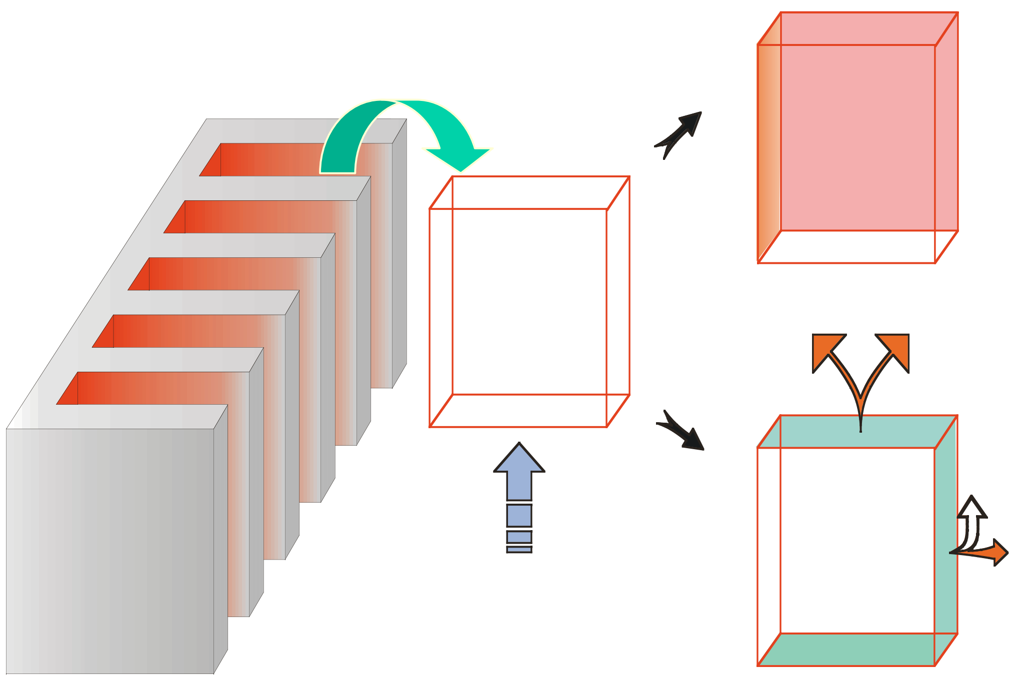
Where:

[illegible]

[illegible]

[illegible]

Interior Surfaces



Channel flow

- Elenbaas model with adjustment for end wall
- combined flow : developing + fully developed

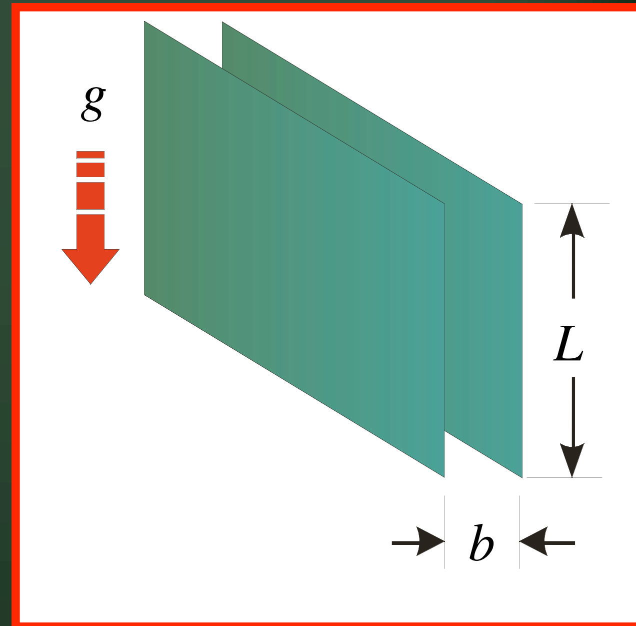
Control surfaces

- open surfaces with energy migration

Parallel Plates Model

Elenbaas, 1941

Churchill, 1977



fd – fully developed

dev – developing flow

– body gravity function

– Prandtl number function

Comprehensive Model

diffusion

channel flow

external boundary layer flow

Model Validation

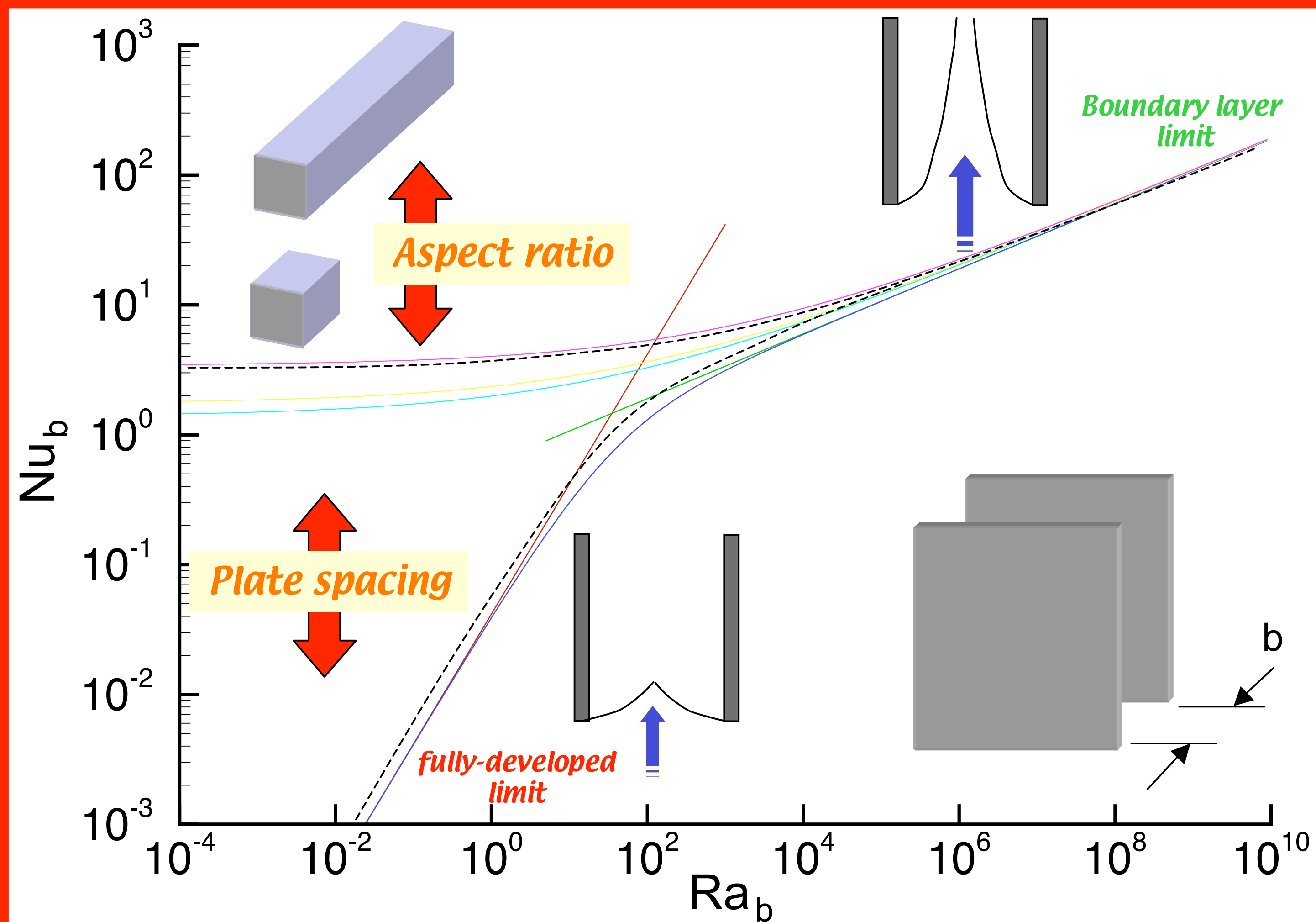
Limiting Cases

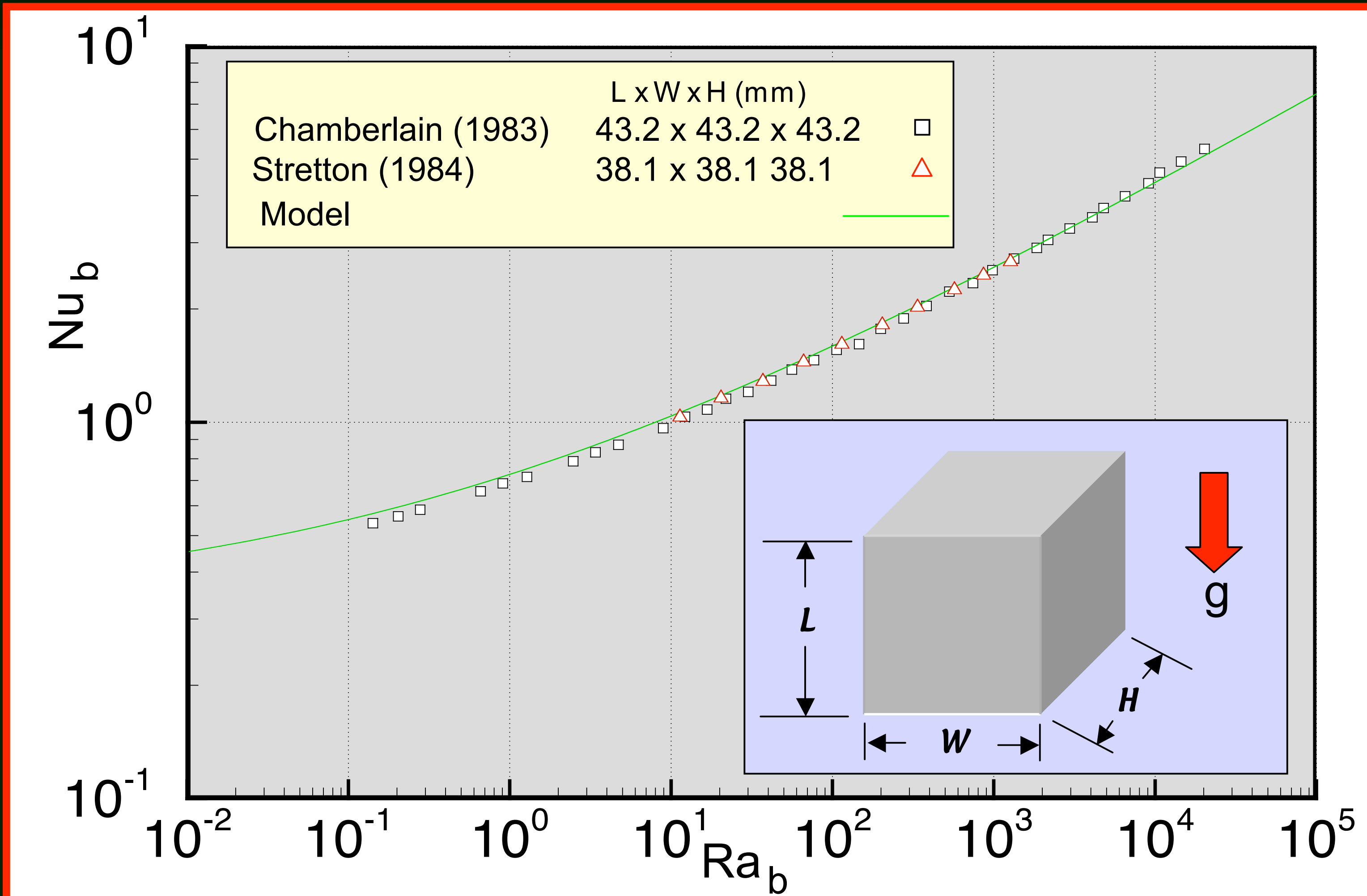
- ➢ cuboids
  - ❶ plate - Karagiozis (1991), Saunders (1936)
  - ❷ cube - Chamberlain (1983), Stretton (1988)
  - ❸ rectangular prism - Clemes (1990)
- ➢ parallel plates
  - ❶ Elenbaas (1942), Aihara (1973), Kennard (1941)

Heat Sinks

- ➢ Karagiozis (1991)
- ➢ Van de Pol & Tierny (1978)

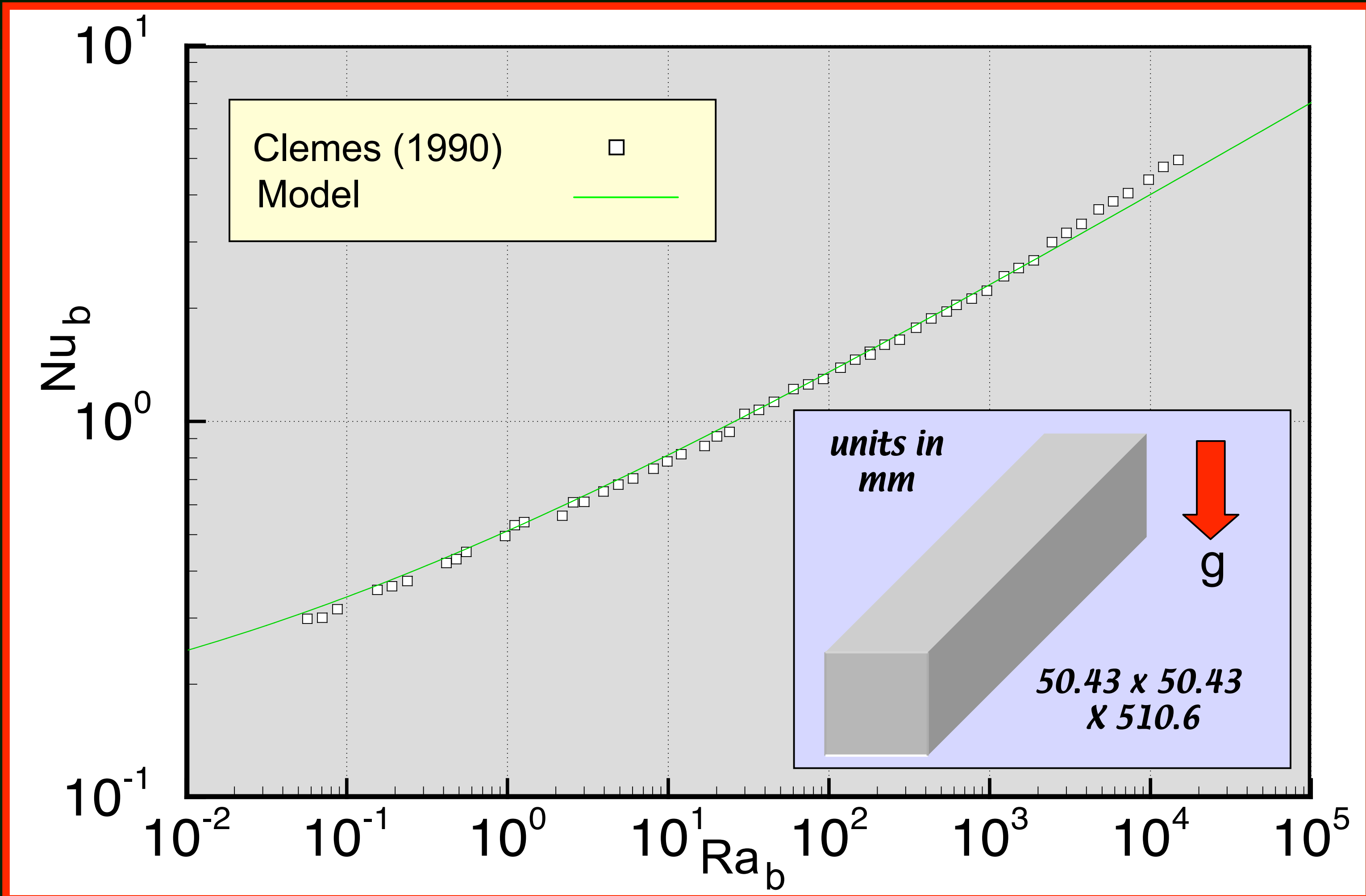
Modelling Domain





$$Nu = Nu_0 + \left\{ Nu_2^{-2} + \left[Nu_3 + Nu_4 \right]^{-2} \right\}^{-1/2} + Nu_1$$

CUBE | PRISM | FLAT PLATE | | | PLATES | HEAT SINK



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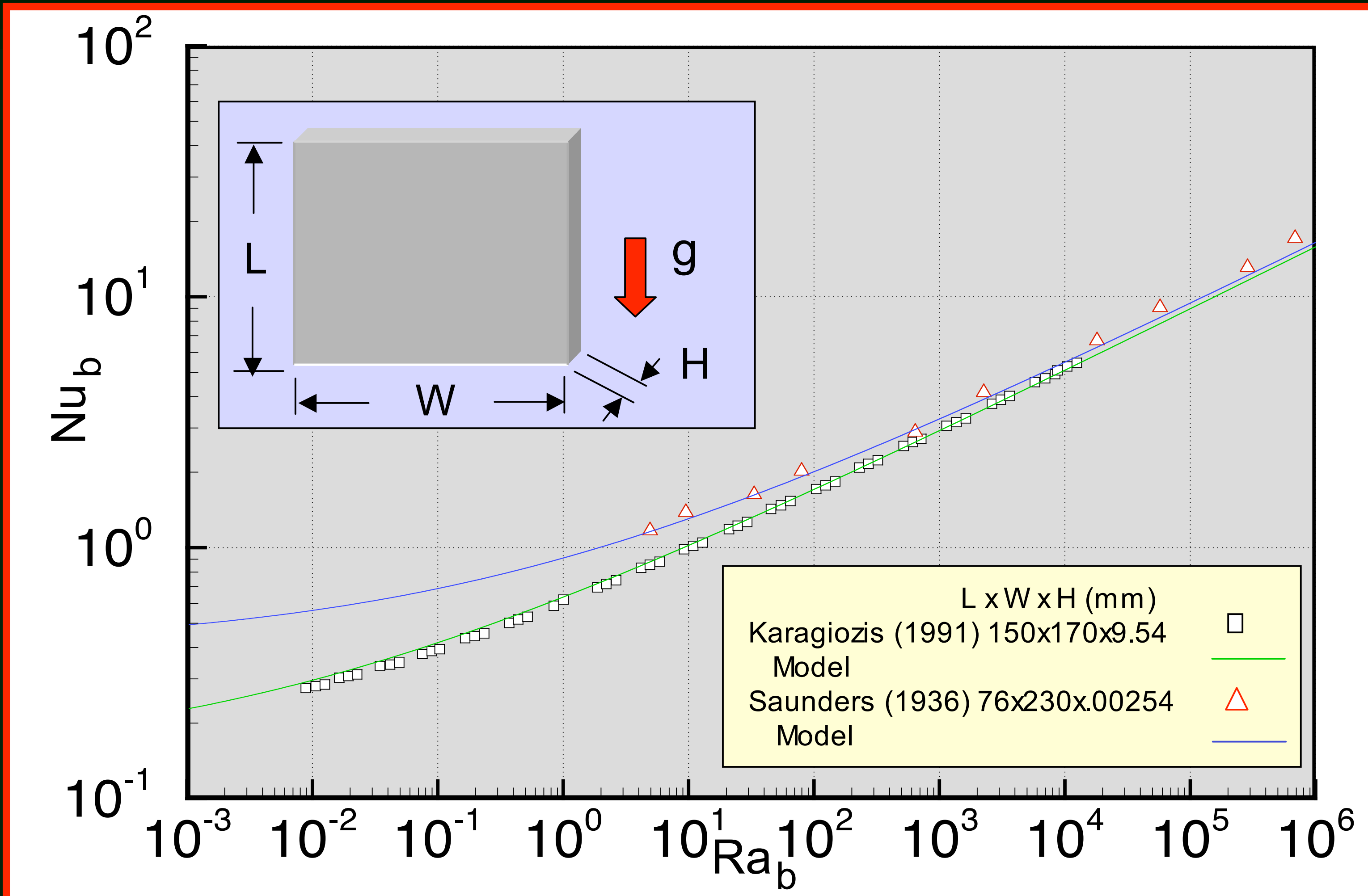

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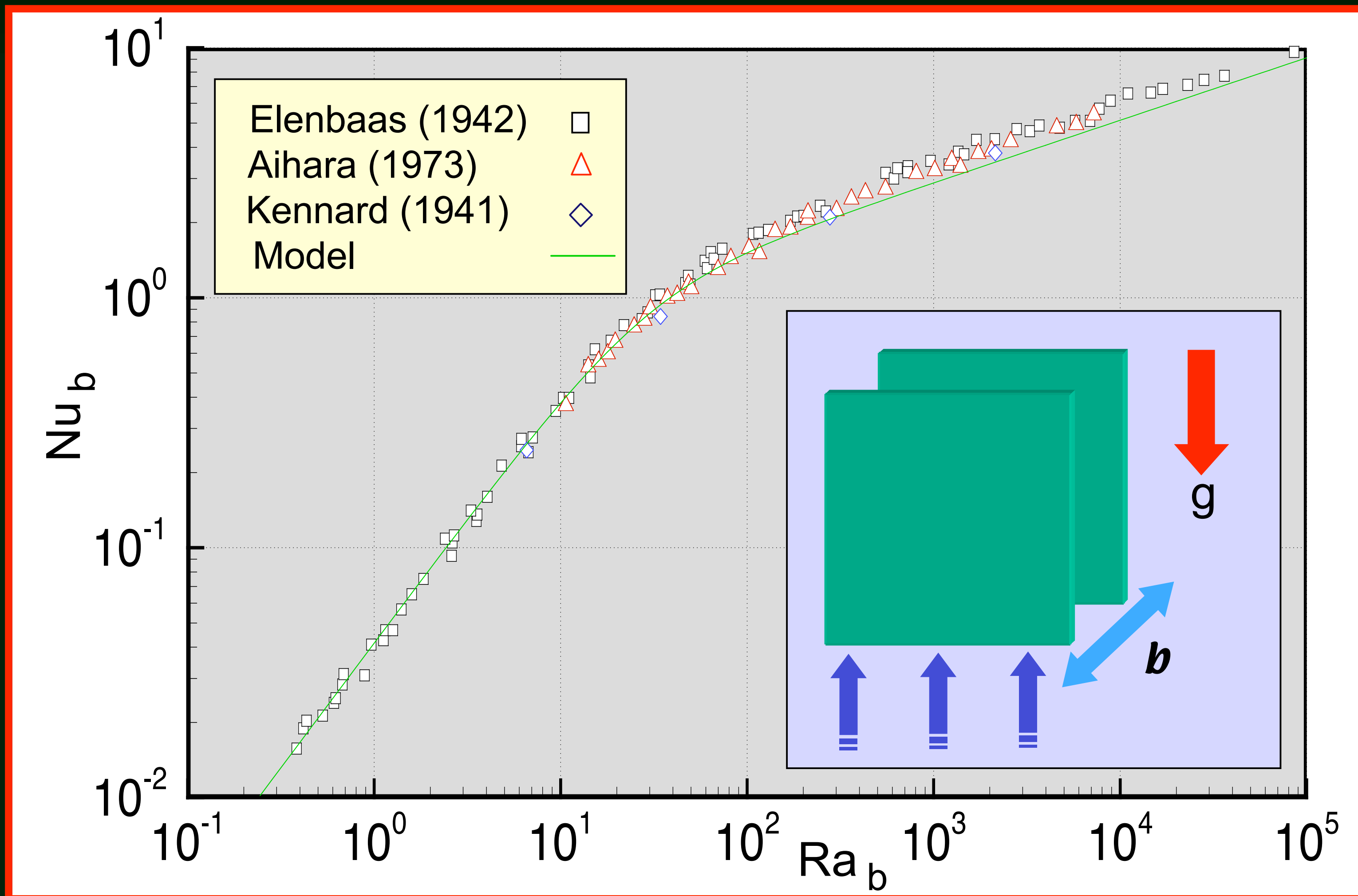
CUBE | PRISM | FLAT PLATE | | | PLATES | HEAT SINK



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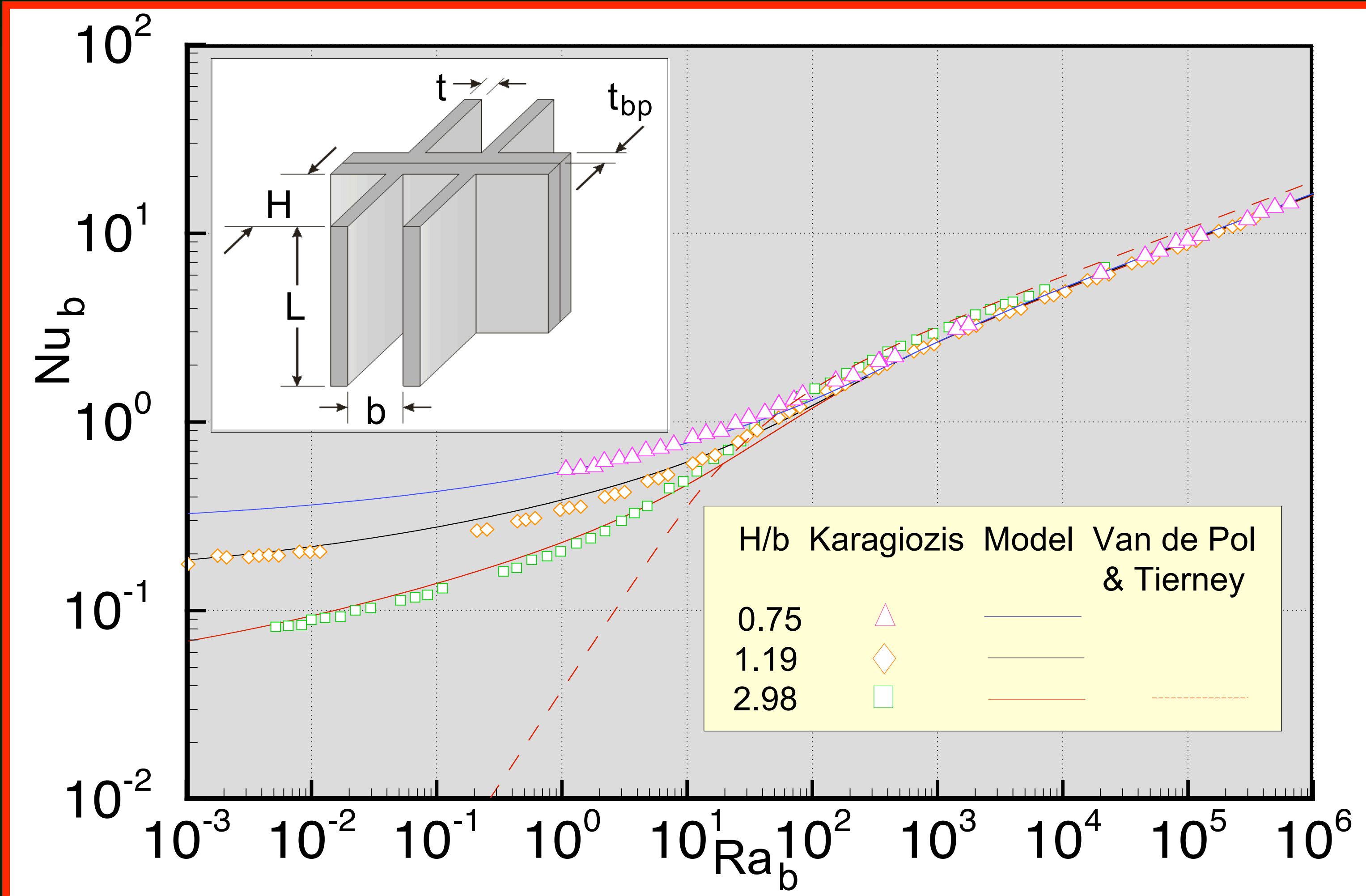
CUBE | PRISM | FLAT PLATE | | | PLATES | HEAT SINK



$$Nu = Nu_0 + \left\{ Nu_2^{-2} + \left[Nu_3 + Nu_4 \right]^{-2} \right\}^{-1/2} + Nu_1$$

CUBE | PRISM | FLAT PLATE | | | PLATES | HEAT SINK

Which is the Right Tool?

Analysis Tool	vs.	**Design Tool**

- design is known a priori
- used to calculate the performance of a given design, i.e. Nu vs. Ra
- cannot guarantee an optimized design

- used to obtain an optimized design for a set of known constraints

i.e. given:
- heat input
- max. temp.
- max. outside dimensions

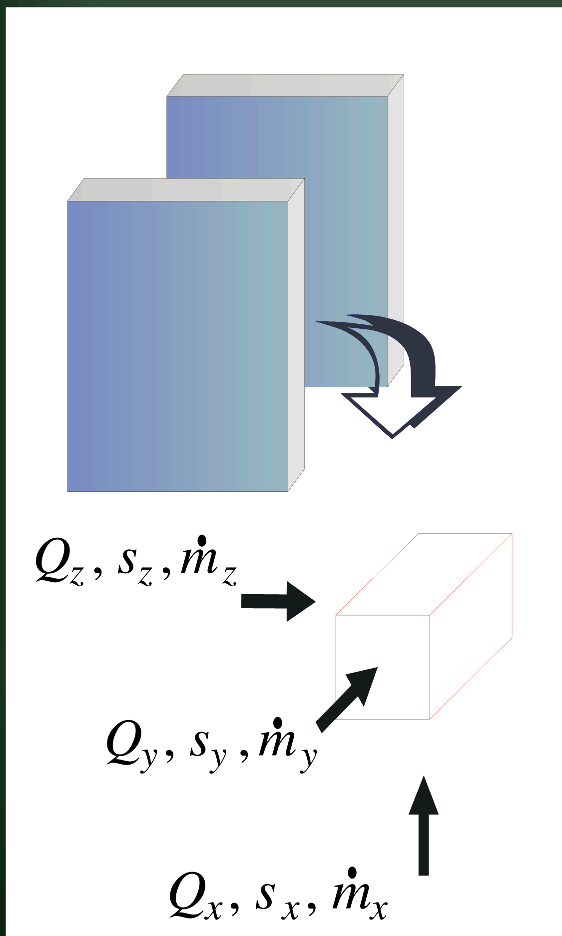
find: the most efficient design

Optimization Using EGM

Why use Entropy Generation Minimization?

- entropy production ∝ amount of energy degraded to a form unavailable for work
- lost work is an additional amount of heat that could have been extracted
- degradation process is a function of thermodynamic irreversibilities e.g. friction, heat transfer etc.
- minimizing the production of entropy, provides a concurrent optimization of all design variables

Entropy Balance (local)



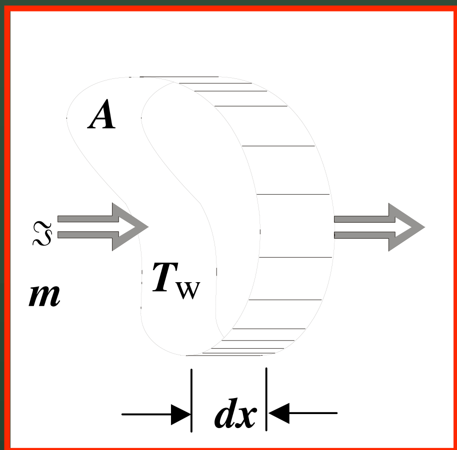
conservation of mass + 1st law of thermodynamics + Gibb's Equation

heat transfer

viscous dissipation

Entropy Balance (external & internal)

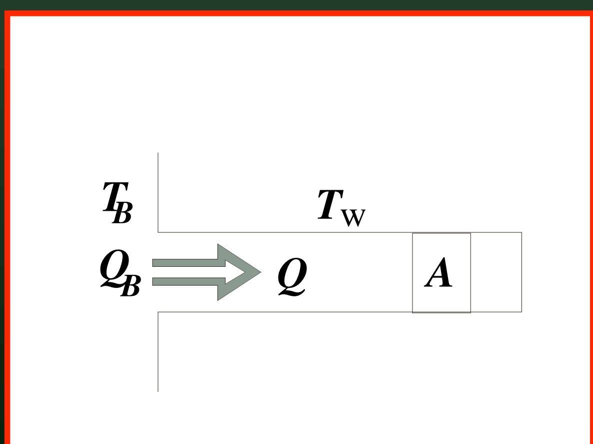
Passage geometry



irreversibilities due to: wall-fluid ΔT

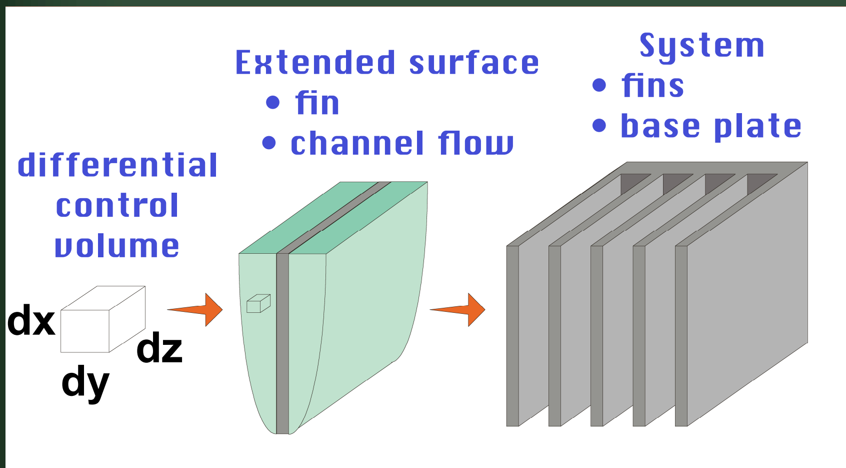
fluid friction

Extended surface



irreversibilities due to base-wall ΔT

Total Entropy Generation



component level

elemental level

differential level

where:

– base heat flow rate

– base - stream temp. difference

– ambient temperature

– drag force

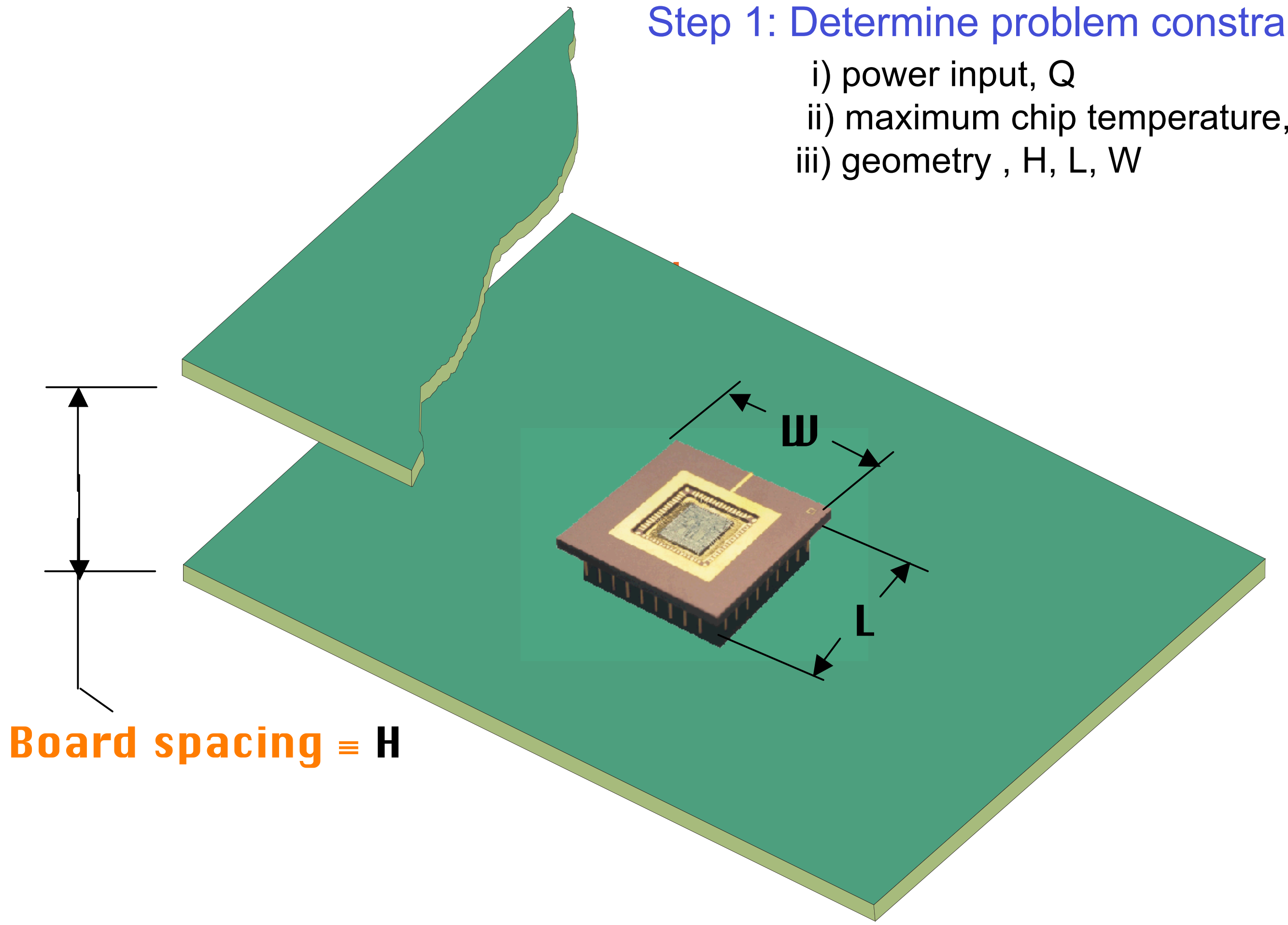
– total fin resistance

- specified

- fan curve

- buoyancy induced

Example: Heat Sink Optimization



Step 1: Determine problem constraints

i) power input, Q

ii) maximum chip temperature, Tmax

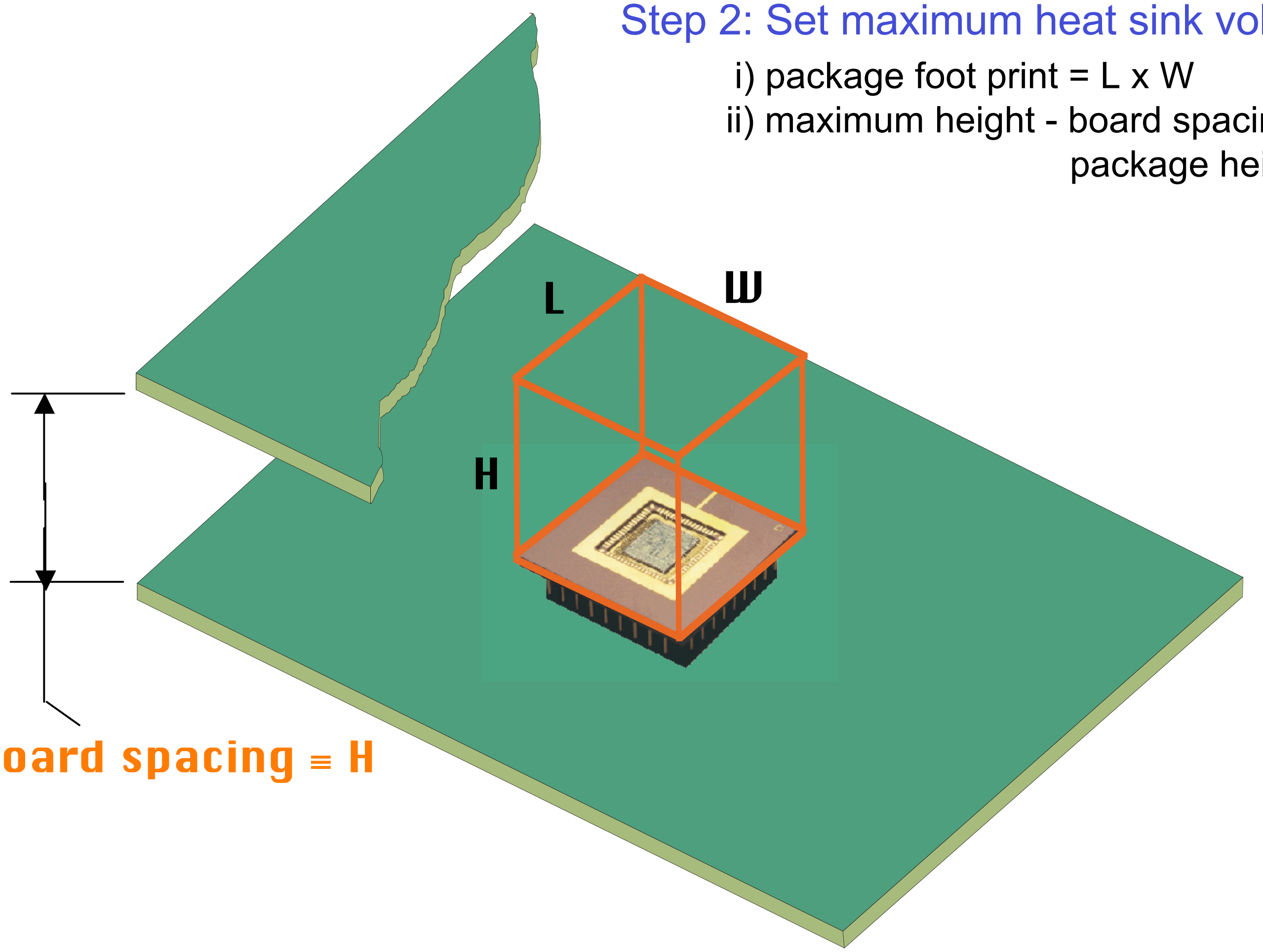
iii) geometry , H, L, W

Example: Heat Sink Optimization

Step 2: Set maximum heat sink volume

i) package foot print = L x W

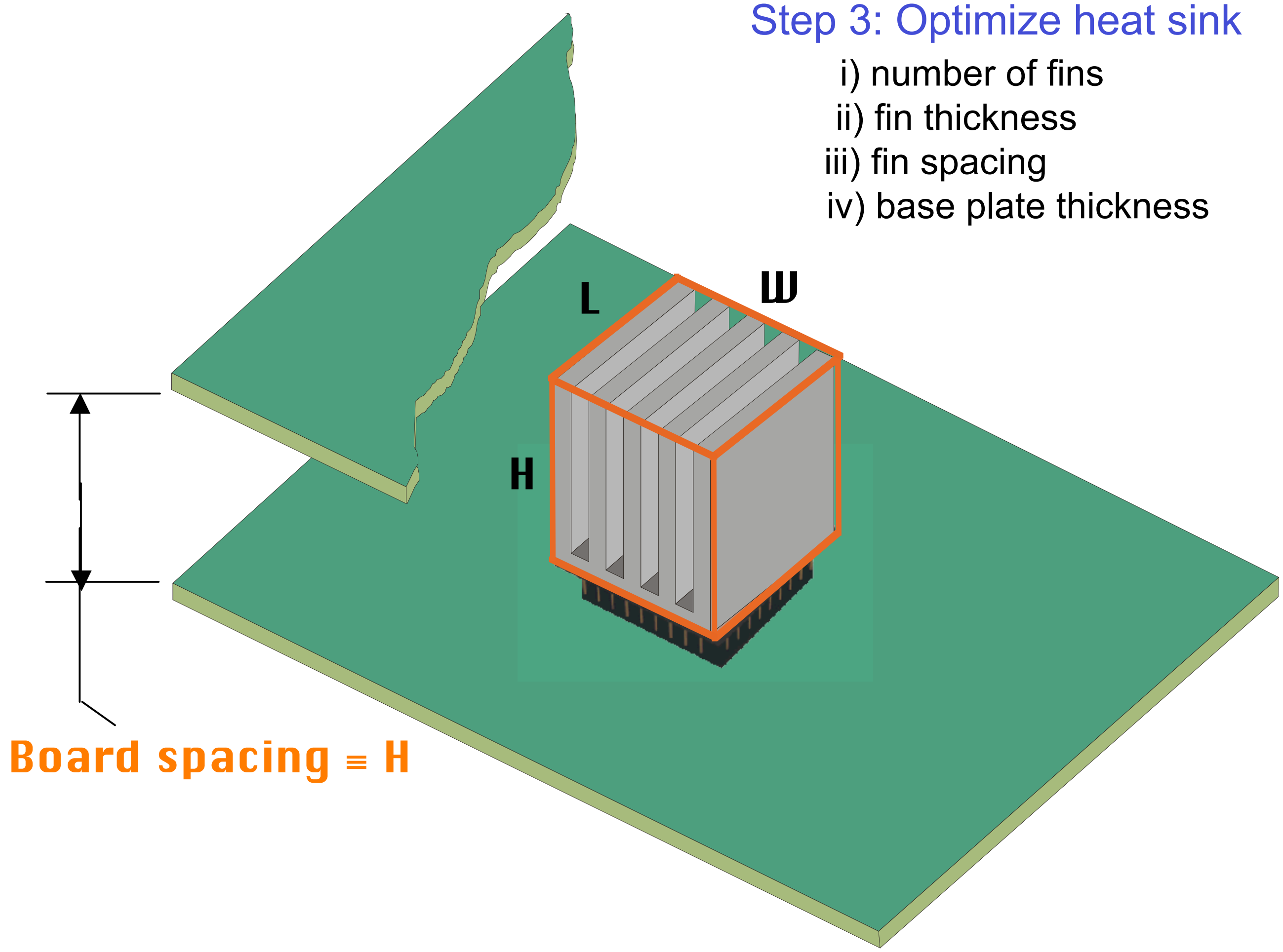
ii) maximum height - board spacing minus package height



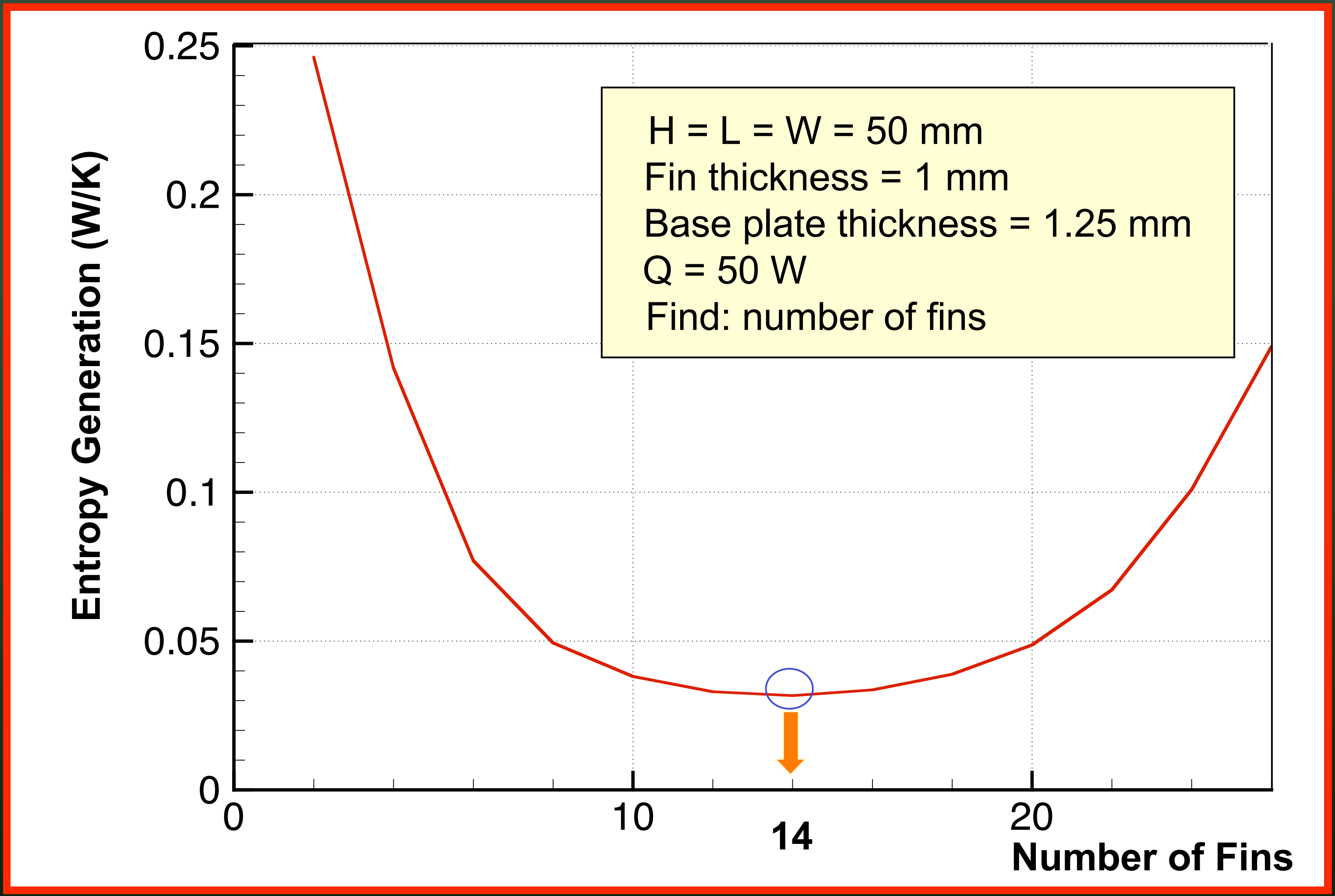
Example: Heat Sink Optimization

Step 3: Optimize heat sink

i) number of fins
ii) fin thickness
iii) fin spacing
iv) base plate thickness



Single Parameter EGM



Multi-Parameter Minimization Procedure

Newton-Raphson Method with Multiple Equations and Unknowns

where:

iterate until

Future Work

Goal: Develop a comprehensive model to find the best heat sink design given a limited set of design constraints

Physical Design
- heat sink type
- material
- weight
- dimensions
- surface finish

Thermal
- maximum volume
- boundary conditions
- max. allowable temp.
- orientation
- flow mechanism

Cost
- labour
- manufacturing
- material

Standards
- noise
- exposure to touch

Summary

- Heat sink design requires both a selection tool & an analysis tool
- Selection is based on:
  - physical constraints - geometry, material, etc.
  - thermal-fluid conditions - bc's, properties, etc.
  - miscellaneous conditions - cost, standards etc.
- Analysis is based on simulating a prescribed design

The End

Karagiozis Heat Sink Model

[illegible]

where:

[illegible]

Modified flat plate model ➛ correction term at low Ra